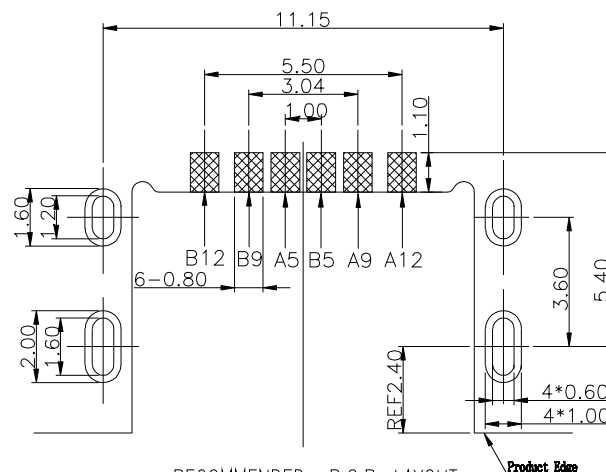
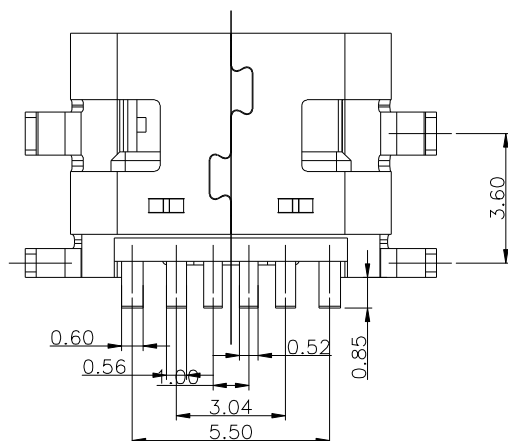
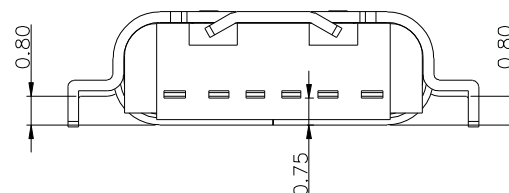
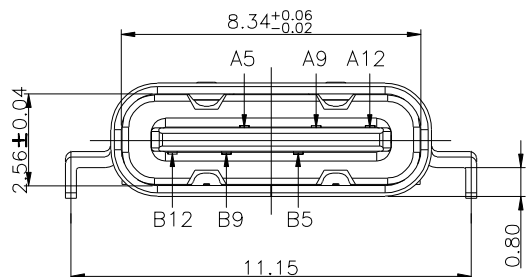
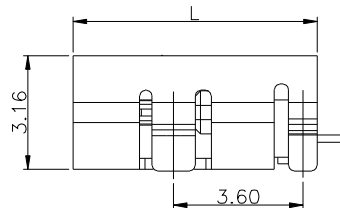
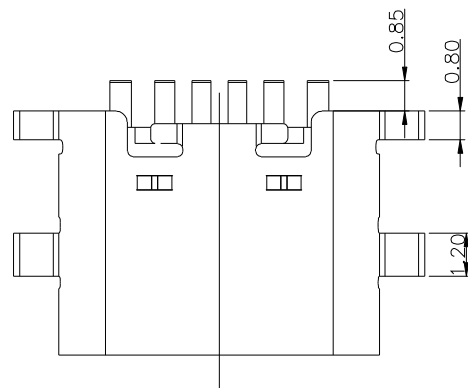




RECOMMENDED P.C.B. LAYOUT
TOLERANCE UNSPECIFIED $\pm 0.05\text{mm}$

PIN ASSIGNMENTS

A5	CC1	B12	GND
A9	VBUS	B9	VBUS
A12	GND	B5	CC2
PIN	SIGNAL NAME	PIN	SIGNAL NAME

L	$L = 6.8$
L	$L = 6.5$

NOTE:

1.MATERIAL SPECIFICATION:

- 1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
- 2.CONTACTS:COPPER ALLOY
- 3.MID PLATE: STAINLESS STEEL
- 4.FRONT SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:

2-1.CONTACTS:

Ni 50u" MIN. UNDER PLATED OVER ALL.

Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.

(GOLD PLATING THICKNESS FOLLOW THE P/N)

PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL:

SEE TABLE1.

2-3.SHIELD PLATE&EMI PLATE:

CLEAR ONLY

3.MECHANICAL PERFORMANCE,

- 3-1.INSERTION FORCE: 0.5~2.0kgf.
- 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
- 3-3.DURABILITY: 5000 CYCLES.

4.ELECTRICAL PERFORMANCE,

- 4-1. CURRENT RATING:3.0A

VOLTAGE RATING:5.0V

4-2. LLCR:

VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.

SHIELD: 50mΩ/MAX.

LLCR MAX. CHANGE OF ALL PINS: 10mΩ.

4-3.INSULATION RESISTANCE: 100MΩ MIN

4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -25°C~+85°C.

6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

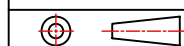


深圳市华宇创精密电子有限公司

TOLERANCE:

X.X ± 0.30
X.XX ± 0.25
X.XXX ± 0.15

X" $\pm 2^\circ$ X.X" $\pm 0.5^\circ$



UNIT: mm [inch]

SCALE:1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

USB TYPE C 母座6P沉板0.8四脚DIP

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYCW443-USBC06-XXXB

MOLD NO.

APPROVED BY:

邱敏

DATE :

2014-02-23

DRAW NO:

HYC-2307191939

SHEET NO.

1 OF 1